Міскоснір			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling
Semiconductor Device Type:	NUA	16 VQFN 4x4x0.9mm NiPdAu								e4
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	20.74	(mg) Total	Mold Compound	% ot Total Weight	50.70
Silica, fused	60676-86-0	Mold Compound	45.630	18.663	456.300		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.459	1.006	24,590		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.459	1.006	24,590	-	Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.152	0.062	1,521		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	40.810	16.691	408,100			Total	100.00	
Iron	7439-89-6	Lead Frame	0.061	0.025	614	16.73	(mg) Total	Lead Frame	% of Total Weight	40.90
Phosphorous	7723-14-0	Lead Frame	0.016	0.007	164		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.012	0.005	123		Iron	7439-89-6	0.15	
Silver	7440-22-4	Die Attach	0.809	0.331	8,085		Phosphorous	7723-14-0	0.04	
Epoxy resin	68475-94-5	Die Attach	0.210	0.086	2,100		Zinc (Metal)	7440-66-6	0.03	
Copper(II) oxide	1317-38-0	Die Attach	0.032	0.013	315			Total	100.00	
Silicon	7440-21-3	Chip (Die)	5.530	2.262	55,300	0.43	(mg) Total	Die Attach	% of Total Weight	1.05
Gold	7440-57-5	Wire Bond	0.500	0.205	5,000		Silver	7440-22-4	77.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.188	0.486	11,880		Epoxy resin	68475-94-5	20.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.066	0.027	660		Copper(II) oxide	1317-38-0	3.00	
Gold	7440-57-5	Plating on external leads (pins)	0.066	0.027	660			Total	100.00	
		TOTALS:	100.000	40.900	1,000,000	2.26	Total (mg)	Chip (Die)	% of Total Weight	5.53
2015/863/EU (31 March 2015) and 2000/53/EC an pliance with the above EU Directives has been	terials comply wi d 2016/774/EU (E verified via intern	nd-of-Life Vehicles (ELV) without exemption (ze al design controls, supplier declarations, and /c	ro) or analytical tes	t data.	·	0.20	Doped Silicon (mg) Total	Total Wire Bond	100.00 100.00 % of Total Weight	0.50
2015/863/EU (31 March 2015) and 2000/53/EC an apliance with the above EU Directives has been chemical substance is absent from the list above rochip Technology Incorporated's knowledge an	terials comply wi d 2016/774/EU (Eu /erified via intern e, the chemical su d belief as of the	h EU Directives: 2002/95/EC (27 January 2003) nd-of-Life Vehicles (ELV) without exemption (ze al design controls, supplier declarations, and /o bstance is NOT an intentional ingredient in the date of this document, there is no credible reas	ro) or analytical test semiconductor on to believe th	t data. device and, t nat the unavoid	o the best of dable		·	Total	100.00	0.50
2015/863/EU (31 March 2015) and 2000/53/EC an opliance with the above EU Directives has been chemical substance is absent from the list above ochip Technology Incorporated's knowledge an urity concentration of the chemical substance, if ding compounds used by Microchip meet the UL	terials comply with d 2016/774/EU (En verified via intern e, the chemical su d belief as of the any, is not below .94 V0 flammabilit	h EU Directives: 2002/95/EC (27 January 2003) rd-of-Life Vehicles (ELV) without exemption (2e al design controls, supplier declarations, and /c bstance is NOT an intentional ingredient in the date of this document, there is no credible reas the threshold of regulatory concern for any reg y standard for plastics. You can access the UL	ro) or analytical test semiconductor on to believe th gulatory schem	t data. device and, t nat the unavoin e world-wide.	o the best of dable		(mg) Total	Total Wire Bond	100.00 % of Total Weight	0.50
2015/863/EU (31 March 2015) and 2000/53/EC an apliance with the above EU Directives has been chemical substance is absent from the list above ochip Technology Incorporated's knowledge an urity concentration of the chemical substance, if ding compounds used by Microchip meet the UL rt at http://ul.com/global/eng/pages/offerings/im protective "tubes" in which the specific product	terials comply wi d 2016/774/EU (Er verified via intern e, the chemical su d belief as of the any, is not below .94 V0 flammabilit dustries/chemical t is shipped are m	The UDirectives: 2002/95/EC (27 January 2003) ad-of-Life Vehicles (ELV) without exemption (2e al design controls, supplier declarations, and /c bstance is NOT an intentional ingredient in the date of this document, there is no credible reas the threshold of regulatory concern for any re y standard for plastics. You can access the UL s/plastics/ made from polyvinyl chloride (PVC) plastic. "Win	ro) or analytical tesi semiconductor on to believe th gulatory schem iQTM family of	t data. device and, t hat the unavoid e world-wide. databases to	o the best of dable obtain a test		(mg) Total	Total Wire Bond 7440-57-5	100.00 % of Total Weight 100.00	0.50
2015/863/EU (31 March 2015) and 200/53/EC an opliance with the above EU Directives has been ochemical substance is absent from the list above ochip Technology Incorporated's knowledge an urity concentration of the chemical substance, if ding compounds used by Microchip meet the UL rt at http://ul.com/global/eng/pages/offerings/im protective "tubes" in which the specific product sing slip on the outer box and certain "reels" ma ochip Technology Incorporated believes the infi- conductor devices in their original packing mat ochip Technology Incorporated cannot guarante rided in Material Safety Data Sheets provided by si age weight of these parts and the average weigh	terials comply wild d 2016/774/EU (Er verified via intern e, the chemical su d belief as of the any, is not below .94 V0 flammabilit dustries/chemical t is shipped are m y be made from F ormation in this for erials is true and se the completenc raw material sup becontract assem t of anticipated s	th EU Directives: 2002/95/EC (27 January 2003) nd-of-Life Vehicles (ELV) without exemption (ze al design controls, supplier declarations, and /c lostance is NOT an intentional ingredient in the date of this document, there is no credible reas <i>t</i> the threshold of regulatory concern for any rey y standard for plastics. You can access the UL s/plastics/ ade from polyvinyl chloride (PVC) plastic. "Win PVC plastic. prm concerning substances restricted by RoHS correct to the best of its knowledge and belief, ses and accuracy of data in this form because it pliers. Supplier information is often protected fr blers and raw material suppliers. Information is ignificant toxic metals components. These estin	ro) or analytical test semiconductor on to believe th gulatory schem iQTM family of dow envelopes in Microchip Te as of the date li has been comp rom disclosure provided only	t data. device and, t nat the unavoic e world-wide. databases to s" used to hold echnology Inc isted in this fo piled based or as trade secra as estimates d	o the best of dable obtain a test d the corporated's orm. n the ranges ets and of the	0.54	(mg) Total Gold	Total Wire Bond 7440-57-5 Total Plating on external	100.00 % of Total Weight 100.00 100.00	
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